Midas Components Limited
Electra House
32 Southtown Road
Great Yarmouth
Norfolk
NR31 0DU
England

Telephone +44 (0)1493 602602
Fax +44 (0)1493 665111
Email sales@midasdisplays.com
Website www.midasdisplays.com

Specification	
Part Number:	MCCOG128064B12W-BNMLW
Version:	1
Date:	2016/02/25

Revision

VERSION	DATE	REVISED PAGE NO.	Note
0	2016/01/25		First issue

Resolution	128 x 64
Appearance	White on Blue
Logic Voltage	3.3V
Interface	Parallel
Fonts	English / Japanese
Display Mode	Transmissive
LC Type	STN
Module Size	54.6 x 42.2 x 4.33 mm
Operating Temperature	-20°C ~ +70°C
Construction	COG
LED Backlight	White LED

RoHS
2011/65/EU

Contents

1.General Specification

The Features is described as follow:

- Module dimension: 54.6 x 42.2 x 4.33 mm
- View area: 50.6 x 31.0 mm
- Active area: 46.577 x 27.697 mm
- LCD type: STN Negative, Blue Transmissive
- Duty/ Bias: 1/65 DUTY,1/7BIAS
- View direction: 12 o’clock
- Backlight Type: LED White
- IC:ST7565P

Midas LCD Part Number System

MC	COG	132033	A	*	6	W	*	*	-	S	N	T	L	W	*	*
1	2	3	4	5	6	7	8	9	-	10	11	12	13	14	15	16

1 = **MC:** Midas Components

2 = **Blank:** COB (chip on board) **COG**: chip on glass

3 = **No of dots** (e.g. 240064 = 240 x 64 dots) (e.g. 21605 = 2 x 16 5mm C.H.)

4 = **Series**

5 = **Series Variant:** A to Z **– see addendum**

6 = **3:** 3 o'clock **6:** 6 o'clock **9**: 9 o'clock **12**: 12 o'clock

7 = **S**: Normal (0 to + 50 deg C) **W:** Wide temp. (-20 to + 70 deg C) **X:** Extended temp (-30 + 80 Deg C)

8 = **Character Set**

Blank: Standard (English/Japanese)
C: Chinese Simplified (Graphic Displays only)
CB: Chinese Big 5 (Graphic Displays only)
H: Hebrew
K: European (std) (English/German/French/Greek)
L: English/Japanese (special)
M: European (English/Scandinavian)
R: Cyrillic
W: European (English/Greek)
U: European (English/Scandinavian/Icelandic)
J: Asian/Arabic

9 = **Bezel Height** (where applicable / available)

	Top of Bezel to Top of PCB	Common (via pins 1 and 2)	Array or Edge Lit
Blank	9.5mm / not applicable	Common	Array
2	8.9 mm	Common	Array
3	7.8 mm	Separate	Array
4	7.8 mm	Common	Array
5	9.5 mm	Separate	Array
6	7 mm	Common	Array
7	7 mm	Separate	Array
8	6.4 mm	Common	Edge
9	6.4 mm	Separate	Edge
A	5.5 mm	Common	Edge
B	5.5 mm	Separate	Edge
D	6.0mm	Separate	Edge
E	5.0mm	Separate	Edge
F	4.7mm	Common	Edge
G	3.7mm	Separate	EL

10 = **T:** TN **S**: STN **B:** STN Blue **G:** STN Grey **F:** FSTN **F2:** FFSTN **V:** VATN **Z:** Zero Power (Bi-Stable)

11 = **P:** Positive **N**: Negative

12 = **R:** Reflective **M**: Transmissive **T:** Transflective

13 = **Backlight: Blank:** Reflective **L:** LED

14 = **Backlight Colour: Y:** Yellow-Green **W:** White **B:** Blue **R:** Red **A:** Amber **O:** Orange **G:** Green **RGB:** R.G.B.

If Z (Zero Power): WB: White on blue **GB:** Green on black **YB:** Yellow on black **YPB:** Yellow on pink and/or blue

15 = **Driver Chip: Blank:** Standard **I:** I²C **T:** Toshiba T6963C **A:** Avant SAP1024B **R:** Raio RA8835

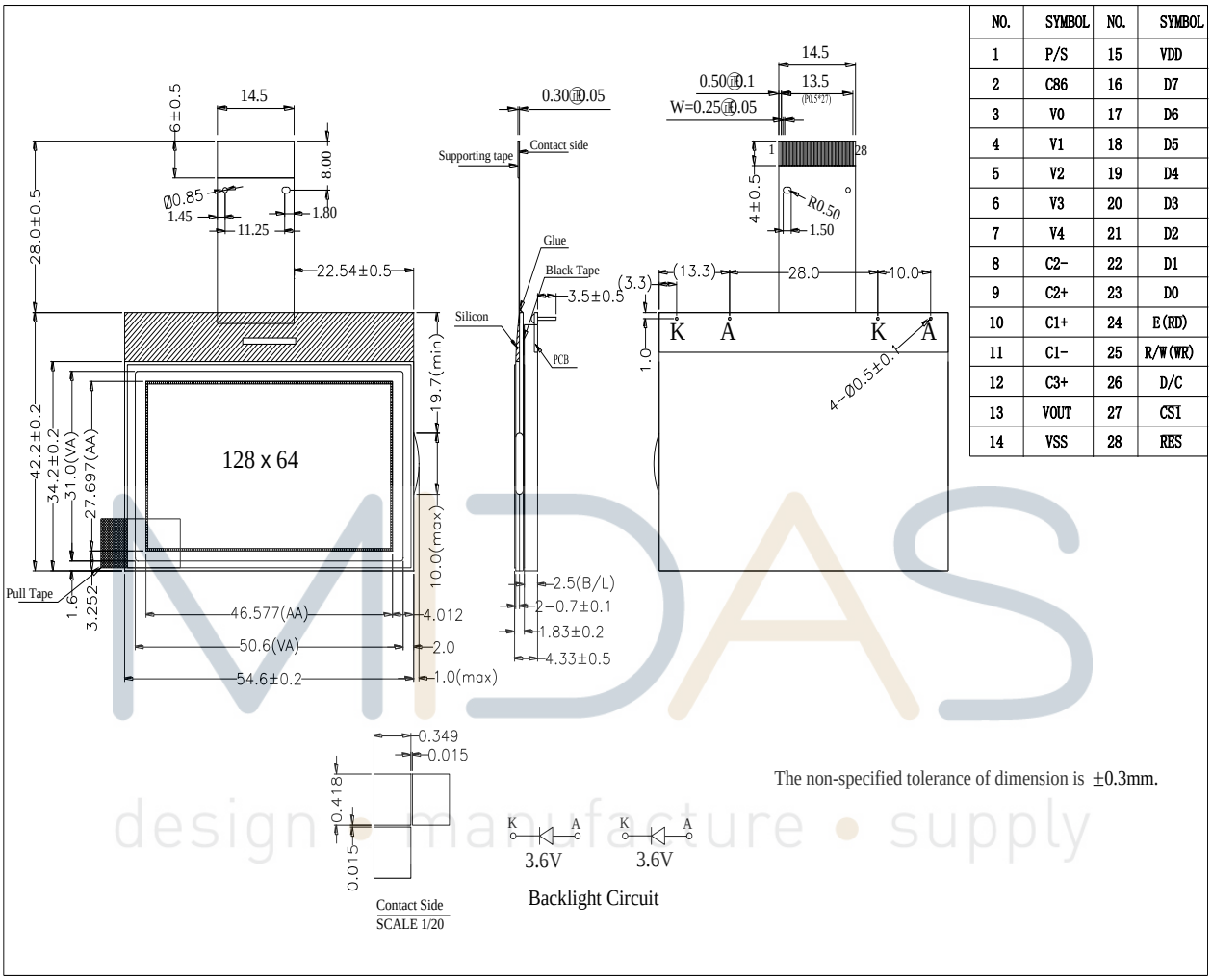
16 = **Voltage Variant**: e.g. **3** = 3v

3.Interface Pin Function

Pin No.	Symbol	Description
1	P/S	This pin configures the interface to be parallel mode or serial mode. P/S = “H”: Parallel data input/output. P/S = “L”: Serial data input.
2	C86	This is the MPU interface selection pin. C86 = “H”: 6800 Series MPU interface. C86 = “L”: 8080 Series MPU interface.
3	V0	This is a multi-level power supply for the liquid crystal drive. The voltage Supply applied is determined by the liquid crystal cell, and is changed through the use of a resistive voltage divided or through changing the impedance using an op. amp. Voltage levels are determined based on Vss, and must maintain the relative magnitudes shown below. V0 ≧V1 ≧V2 ≧V3 ≧V4 ≧Vss
4	V1	
5	V2	
6	V3	
7	V4	
8	C2-	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2P terminal
9	C2+	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2N terminal.
10	C1+	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1N terminal.
11	C1-	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1P terminal.
12	C3+	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1N terminal.
13	VOUT	Voltage converter input/output pin Connect this pin to VSS through capacitor.
14	VSS	Ground
15	VDD	Power supply
16	D7	This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit Standard MPU data bus. When the serial interface (SPI-4) is selected (P/S = “L”) : D7 : serial data input (SI) ; D6 : the serial clock input (SCL).
17	D6	
18	D5	

19	D4	D0 to D5 should be connected to VDD or floating. When the chip select is not active, D0 to D7 are set to high impedance.
20	D3	
21	D2	
22	D1	
23	D0	
24	E(/RD)	When connected to 8080 series MPU, this pin is treated as the “/RD” signal of the8080 MPU and is LOW-active. The data bus is in an output status when this signal is “L”. When connected to 6800 series MPU, this pin is treated as the “E” signal of the6800 MPU and is HIGH-active.This is the enable clock input terminal of the 6800 Series MPU.
25	R/W(/WR)	When connected to 8080 series MPU, this pin is treated as the “/WR” signal of the8080 MPU and is LOW-active. The signals on the data bus are latched at the rising edge of the /WR signal. When connected to 6800 series MPU, this pin is treated as the “R/W” signal of the6800 MPU and decides the access type : When R/W = “H”: Read. When R/W = “L”: Write
26	D/C	This is connect to the least significant bit of the normal MPU address bus, and it determines whether the data bits are data or command.
27	/CS1	This is the chip select signal
28	/RES	When /RES is set to “L”, the register settings are initialized (cleared). The reset operation is performed by the /RES signal level.

4.Contour Drawing



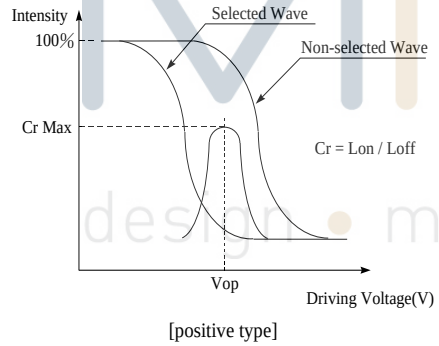
NO.	SYMBOL	NO.	SYMBOL
1	P/S	15	VDD
2	C86	16	D7
3	V0	17	D6
4	V1	18	D5
5	V2	19	D4
6	V3	20	D3
7	V4	21	D2
8	C2-	22	D1
9	C2+	23	D0
10	C1+	24	E(RD)
11	C1-	25	R/W(WR)
12	C3+	26	D/C
13	VOUT	27	CSI
14	VSS	28	RES

The non-specified tolerance of dimension is ±0.3mm.

5.Optical Characteristics

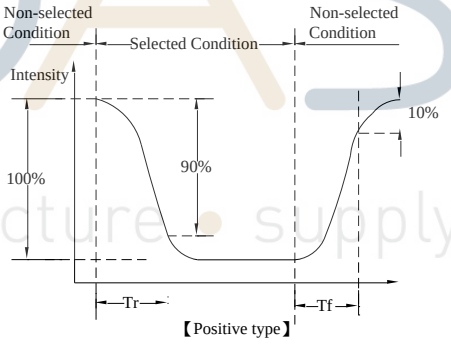
Item	Symbol	Condition	Min	Typ	Max	Unit
View Angle	θ	CR≧2	0	—	45	ψ= 180°
	θ	CR≧2	0	—	25	ψ= 0°
	θ	CR≧2	0	—	35	ψ= 90°
	θ	CR≧2	0	—	35	ψ= 270°
Contrast Ratio	CR	—	3	—	—	—
Response Time	T rise	—	—	—	250	ms
	T fall	—	—	—	250	ms

Definition of Operation Voltage (Vop)



[positive type]

Definition of Response Time (Tr , Tf)



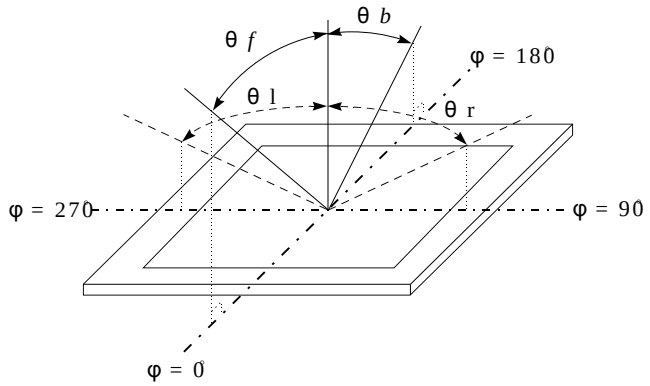
【Positive type】

Conditions :

Operating Voltage : Vop Viewing Angle(θ，φ) : 0°， 0°

Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

Definition of viewing angle(CR≧2)



6.Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	T_{OP}	-20	–	+70	℃
Storage Temperature	T_{ST}	-30	–	+80	℃
Power Supply Voltage	VDD	-0.3	–	3.6	V
Power supply voltage (VDD standard)	V0, VOUT	-0.3	–	14.5	V
Power supply voltage (VDD standard)	V1, V2, V3, V4	-0.3	–	V0+0.3	V

7.Electrical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage For Logic	V_{DD}-V_{SS}	—	3.2	3.3	3.4	V
Supply Voltage For LCM	V_{OP}	Ta=-20℃	—	—	—	V
		Ta=25℃	8.6	8.8	9.0	V
		Ta=70℃	—	—	—	V
Supply Current	I_{DD}	V_{DD}=3.3V	—	0.1	—	mA

Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance

8.Backlight Information

Specification

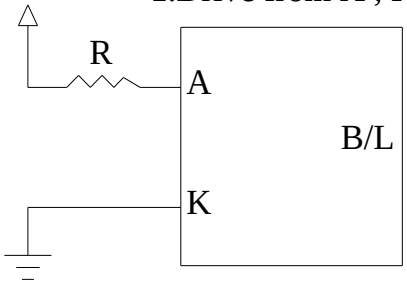
PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	—	32	40	mA	V=3.6V
Supply Voltage	V	3.5	3.6	3.7	V	—
Reverse Voltage	VR	—	—	5	V	—
Luminance (Without LCD)	IV	640	800	—	CD/M^2	ILED=32mA
LED Life Time (For Reference only)	—	—	50K	—	Hr.	ILED=32mA 25℃,50-60%RH, (Note 1)
Color	White					

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.

LED B\L Drive Method

1.Drive from A , K



9.Reliability

Content of Reliability Test (Wide temperature, -20℃~70℃)

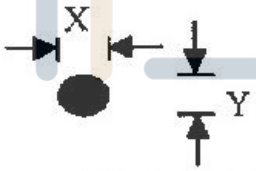
Environmental Test			
Test Item	**Content of Test**	**Test Condition**	**Note**
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30℃ 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs	——
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60℃,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60℃,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20℃ 25℃ 70℃ 30min ← 5min → 30min	-20℃/70℃ 10 cycles	——
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time	——

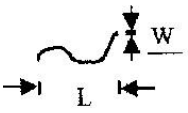
Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

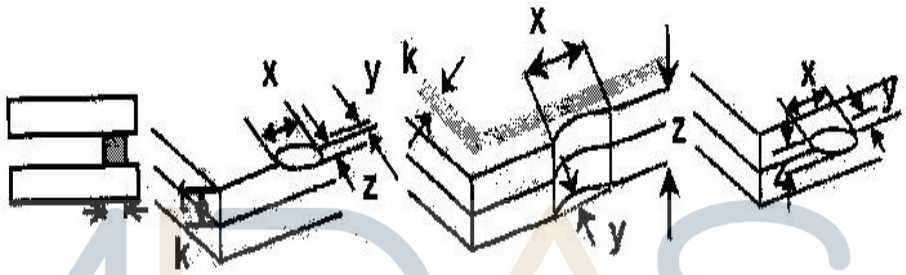
10.Inspection specification

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>01</td><td>Electrical Testing</td><td>1.1 Missing vertical, horizontal segment, segment contrast defect.
1.2 Missing character , dot or icon.
1.3 Display malfunction.
1.4 No function or no display.
1.5 Current consumption exceeds product specifications.
1.6 LCD viewing angle defect.
1.7 Mixed product types.
1.8 Contrast defect.</td><td>0.65</td></tr>
<tr><td>02</td><td>Black or white spots on LCD (display only)</td><td>2.1 White and black spots on display ≦0.25mm, no more than three white or black spots present.
2.2 Densely spaced: No more than two spots or lines within 3mm</td><td>2.5</td></tr>
<tr><td rowspan="2">03</td><td rowspan="2">LCD black spots, white spots, contamination (non-display)</td><td>3.1 Round type : As following drawing
Φ=(x + y) / 2
 

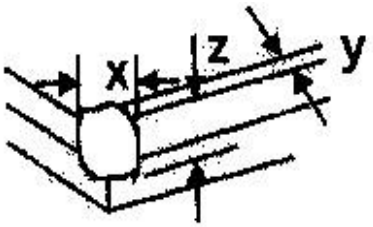
<table>
<tr><th>SIZE</th><th>Acceptable Q TY</th></tr>
<tr><td>Φ≦0.10</td><td>Accept no dense</td></tr>
<tr><td>0.10＜Φ≦0.20</td><td>2</td></tr>
<tr><td>0.20＜Φ≦0.25</td><td>1</td></tr>
<tr><td>0.25＜Φ</td><td>0</td></tr>
</table></td><td>2.5</td></tr>
<tr><td>3.2 Line type : (As following drawing)
 

<table>
<tr><th>Length</th><th>Width</th><th>Acceptable Q TY</th></tr>
<tr><td>---</td><td>W≦0.02</td><td>Accept no dense</td></tr>
<tr><td>L≦3.0</td><td>0.02＜W≦0.03</td><td rowspan="2">2</td></tr>
<tr><td>L≦2.5</td><td>0.03＜W≦0.05</td></tr>
<tr><td>---</td><td>0.05＜W</td><td>As round type</td></tr>
</table></td><td>2.5</td></tr>
<tr><td>04</td><td>Polarizer bubbles</td><td>If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.
<table>
<tr><th>Size Φ</th><th>Acceptable Q TY</th></tr>
<tr><td>Φ≦0.20</td><td>Accept no dense</td></tr>
<tr><td>0.20＜Φ≦0.50</td><td>3</td></tr>
<tr><td>0.50＜Φ≦1.00</td><td>2</td></tr>
<tr><td>1.00＜Φ</td><td>0</td></tr>
<tr><td>Total Q TY</td><td>3</td></tr>
</table></td><td>2.5</td></tr>
</table>

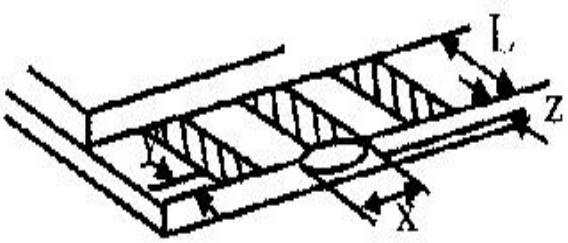
<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>05</td><td>Scratches</td><td>Follow NO.3 LCD black spots, white spots, contamination</td><td></td></tr>
<tr><td>06</td><td>Chipped glass</td><td>
Symbols Define:
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length:

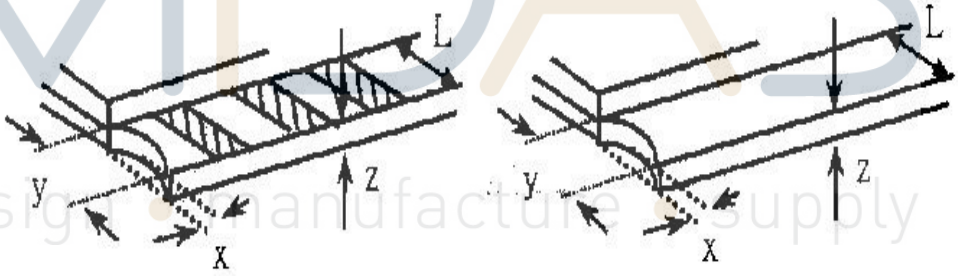
6.1 General glass chip :
6.1.1 Chip on panel surface and crack between panels:


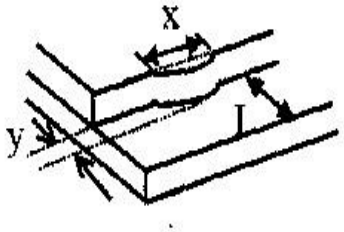
<table>
<tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr>
<tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr>
<tr><td>1/2t＜z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr>
</table>
⊙If there are 2 or more chips, x is total length of each chip.

6.1.2 Corner crack:


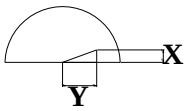
<table>
<tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr>
<tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr>
<tr><td>1/2t＜z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr>
</table>
⊙If there are 2 or more chips, x is the total length of each chip.
</td><td>2.5</td></tr>
</table>

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>06</td><td>Glass crack</td><td>
Symbols :
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length
6.2 Protrusion over terminal :
6.2.1 Chip on electrode pad :


<table>
<tr><th>y: Chip width</th><th>x: Chip length</th><th>z: Chip thickness</th></tr>
<tr><td>y≦0.5mm</td><td>x≦1/8a</td><td>0 ＜ z ≦ t</td></tr>
</table>
6.2.2 Non-conductive portion:


<table>
<tr><th>y: Chip width</th><th>x: Chip length</th><th>z: Chip thickness</th></tr>
<tr><td>y≦ L</td><td>x≦1/8a</td><td>0 ＜ z ≦ t</td></tr>
</table>
⊙If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.
⊙If the product will be heat sealed by the customer, the alignment mark not be damaged.
6.2.3 Substrate protuberance and internal crack.


<table>
<tr><th>y: width</th><th>x: length</th></tr>
<tr><td>y≦1/3L</td><td>x ≦ a</td></tr>
</table>
</td><td>2.5</td></tr>
</table>

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB  X * Y<=2mm2	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	
		12.12 Visual defect outside of VA is not considered to be rejection.	

11.Precautions in use of LCD Modules

(1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.

(2)Don’t make extra holes on the printed circuit board, modify its shape or change the components of LCD module.

(3)Don’t disassemble the LCM.

(4)Don’t operate it above the absolute maximum rating.

(5)Don’t drop, bend or twist LCM.

(6)Soldering: only to the I/O terminals.

(7)Storage: please storage in anti-static electricity container and clean environment.

(8) Midas have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors,capacitors and other passive components will have different appearance and color caused by the different supplier.)

(9)Midas have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Midas have the right to modify the version.)

12.Material List of Components for RoHs

1. Midas hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

   Exhibit A：The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

2.Process for RoHS requirement：

(1) Use the Sn/Ag/Cu soldering surface；the surface of Pb-free solder is rougher than we used before.

(2) Heat-resistance temp.：

Reflow：250℃,30 seconds Max.；

Connector soldering wave or hand soldering：320℃, 10 seconds max.

(3) Temp. curve of reflow, max. Temp.：235±5℃；

Recommended customer's soldering temp. of connector：280℃, 3 seconds.

13.Recommendable Storage

1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
2. Do not place the module near organics solvents or corrosive gases.
3. Do not crush, shake, or jolt the module.